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# **ETROC1 Wire Bonding with 2x2 Sensor**

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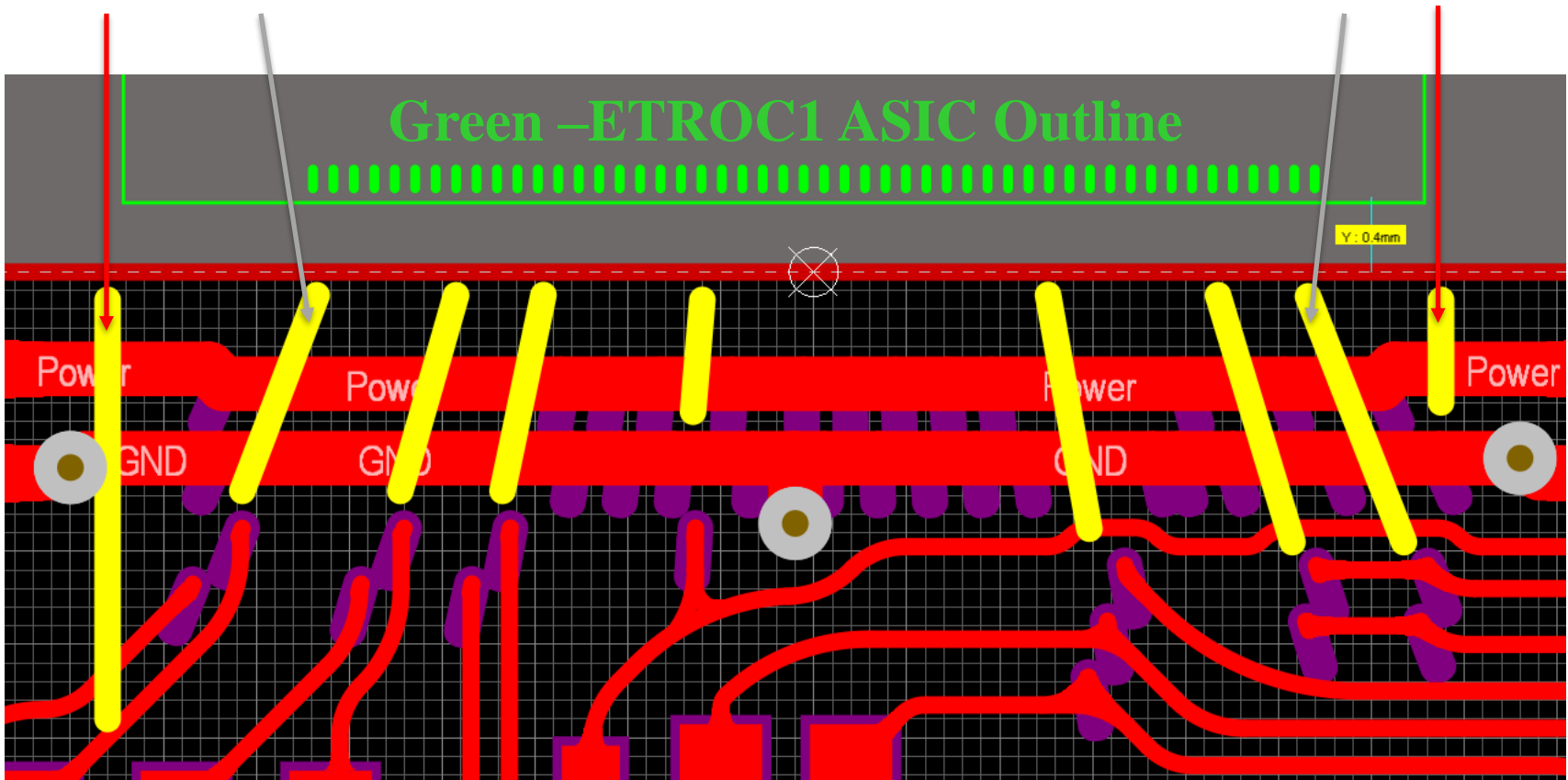
# Overall View of the Assembly

- Board size 32 x 56 mm
- Mounting holes spaced:
  - 24mm horizontally
  - 24mm vertically
- Flex cable overlap 5mm
- Nominal gap between the Flex and ETROC1 0.4mm
- **Center Flex against SilkScreen outline**
- **Use conductive film to attach 2x2 Sensor, align the 4 pixels over the 4 holes in the Sensor mounting pad**



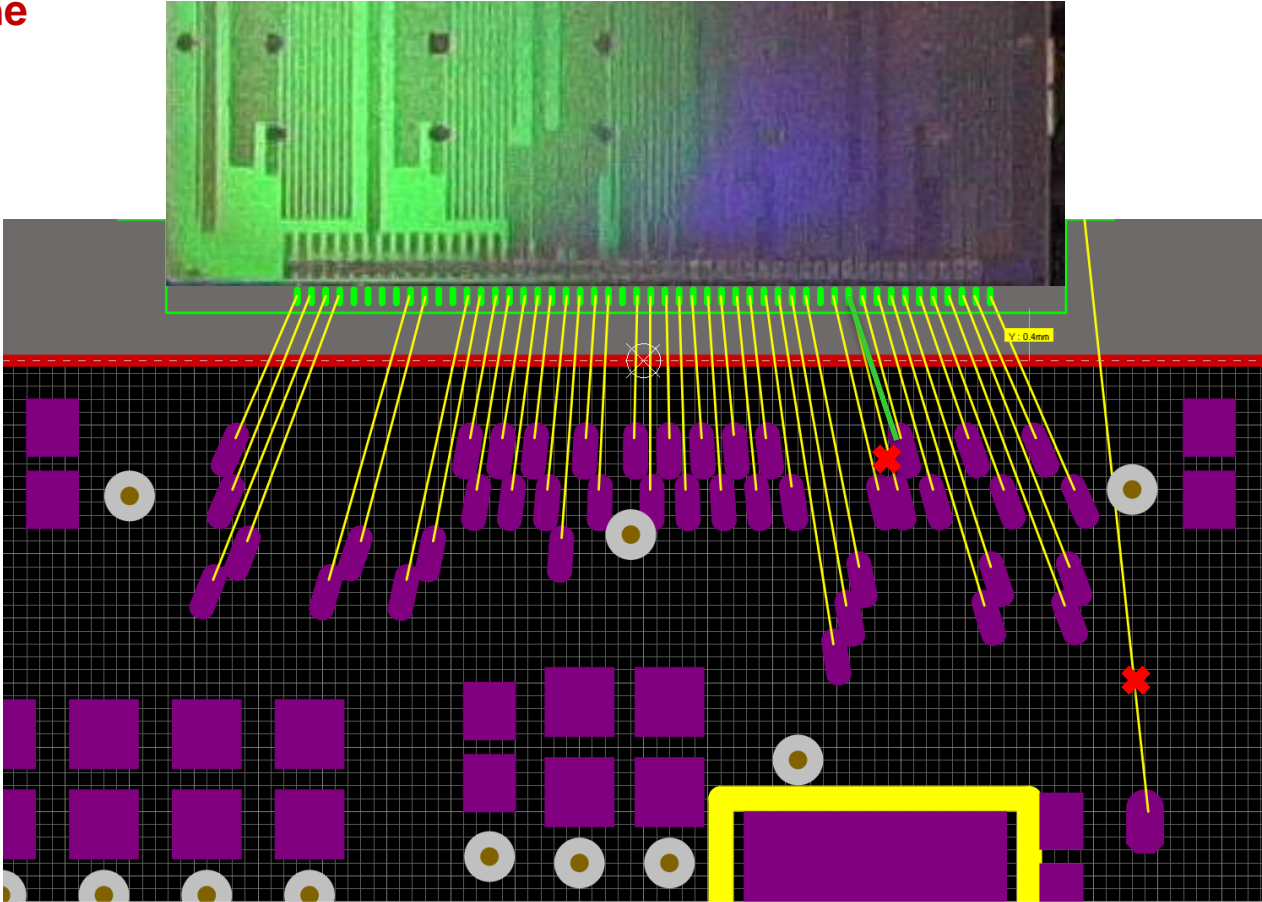
# ETROC1 and Flex Alignment

- Align the ETROC1 chip against the silk screen guidelines (it is not going to be centered on the pad)
- Angled silk screen markers indicate general direction of wire bonding



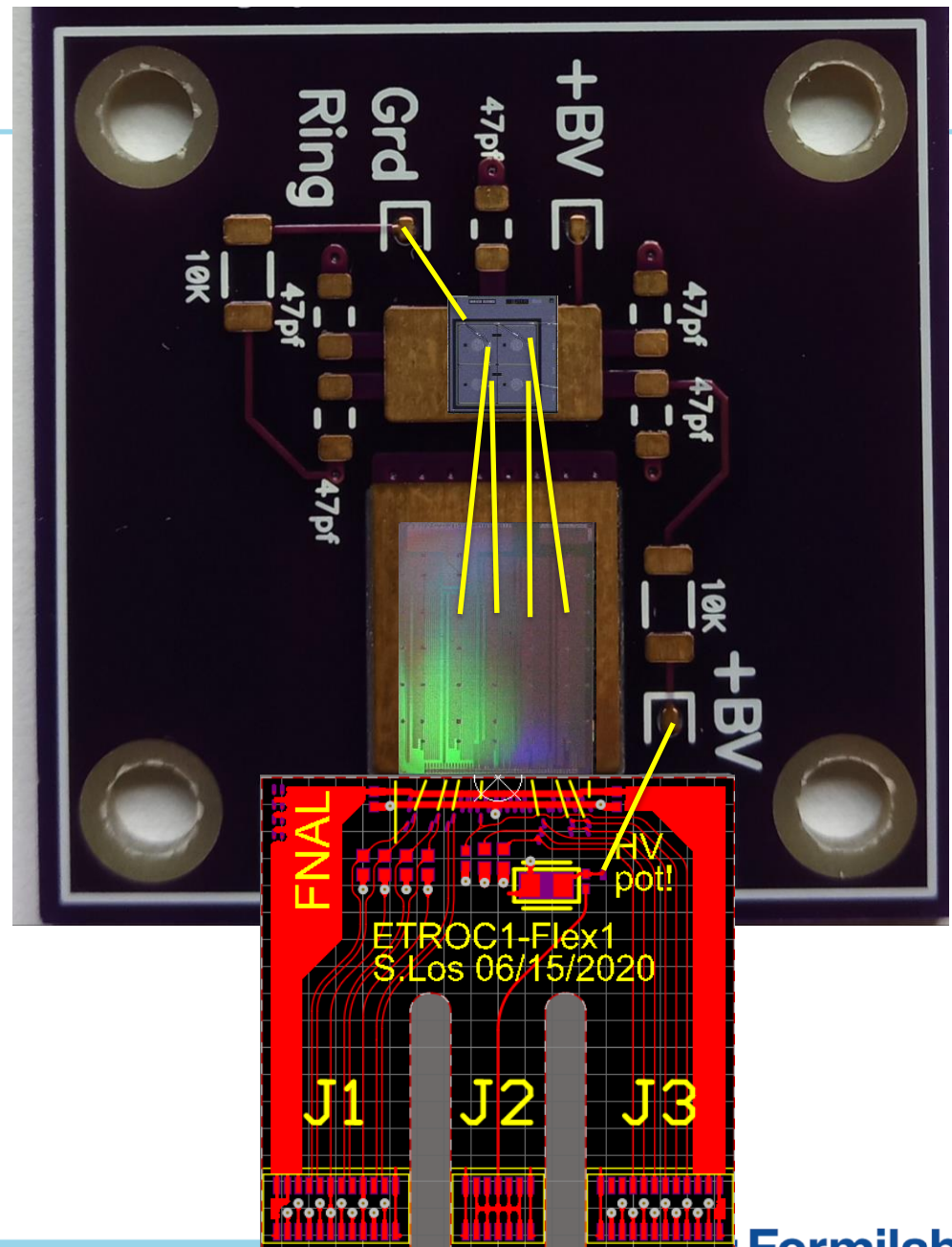
# Wire Bonding ETROC1

See how to bond the right-most +BV long wire in the next slide



# Wire Bonding 2x2 Sensor

- Remove all old wirebonds from the Sensor
- 4 signal wirebonds go to the ETROC1
- 1 wirebond connects Sensor guard ring to a corresponding pad on the board
- 1 wirebond connects Flex HV with the board +BV pad
- See details below



# Details

